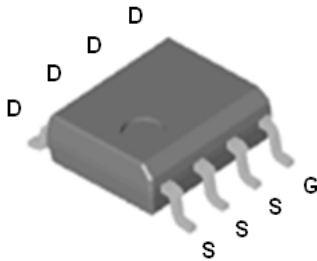


# P1406BV

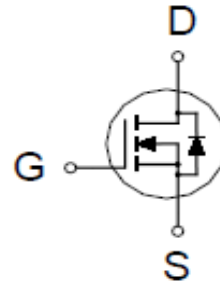
## N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
60V	12.5m $\Omega$ @ $V_{GS} = 10V$	12A



SOP-8



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	$T_A = 25^\circ\text{C}$	12
		$T_A = 70^\circ\text{C}$	10
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	40	A
Avalanche Current	$I_{AS}$	39	
Avalanche Energy	$L = 0.1\text{mH}$	$E_{AS}$	76
Power Dissipation <sup>3</sup>	$P_D$	$T_A = 25^\circ\text{C}$	4
		$T_A = 70^\circ\text{C}$	2.6
Junction & Storage Temperature Range	$T_j, T_{stg}$	-55 to 150	$^\circ\text{C}$

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	$R_{\theta JA}$		30	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		56	
Junction-to-Case	$R_{\theta JC}$		25	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

<sup>3</sup>The Power dissipation is based on  $R_{\theta JA}$   $t \leq 10\text{s}$  value.

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## N-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 °C, Unless Otherwise Noted)

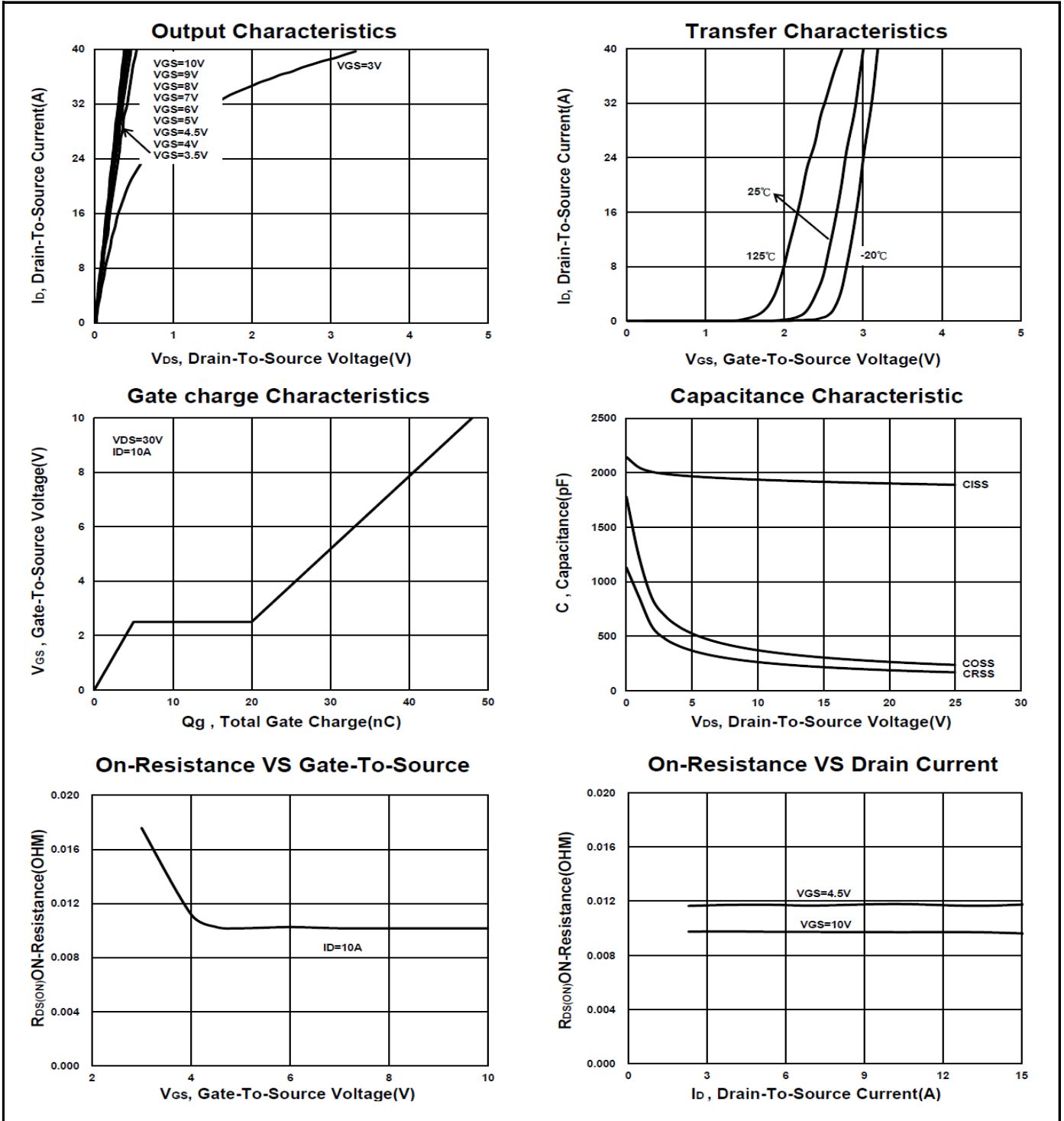
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.3	1.8	2.3	V
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V			1	μA
		V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 55 °C			10	
Drain-Source On-State Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A		11	16	mΩ
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A		9.8	12.5	
Forward Transconductance <sup>1</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A		50		S
<b>DYNAMIC</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 50V, f = 1MHz		1901		pF
Output Capacitance	C <sub>oss</sub>			239		
Reverse Transfer Capacitance	C <sub>rss</sub>			177		
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V, f = 1MHz		0.7		Ω
Total Gate Charge <sup>2</sup>	Q <sub>g(VGS=10V)</sub>	V <sub>DS</sub> = 30V, I <sub>D</sub> = 10A		48		nC
	Q <sub>g(VGS=4.5V)</sub>			27		
Gate-Source Charge <sup>2</sup>	Q <sub>gs</sub>			5		
Gate-Drain Charge <sup>2</sup>	Q <sub>gd</sub>			15		
Turn-On Delay Time <sup>2</sup>	t <sub>d(on)</sub>		V <sub>DS</sub> = 30V, I <sub>D</sub> ≅ 10A, V <sub>GS</sub> = 10V, R <sub>GEN</sub> = 6Ω		20	
Rise Time <sup>2</sup>	t <sub>r</sub>			12		
Turn-Off Delay Time <sup>2</sup>	t <sub>d(off)</sub>			58		
Fall Time <sup>2</sup>	t <sub>f</sub>			10		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>J</sub> = 25 °C)</b>						
Continuous Current	I <sub>S</sub>				3	A
Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10A, V <sub>GS</sub> = 0V			1.3	V
Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 10A, di/dt = 100A /μS		26		nS
Diode Reverse Recovery Charge	Q <sub>rr</sub>				17	

<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup>Independent of operating temperature.

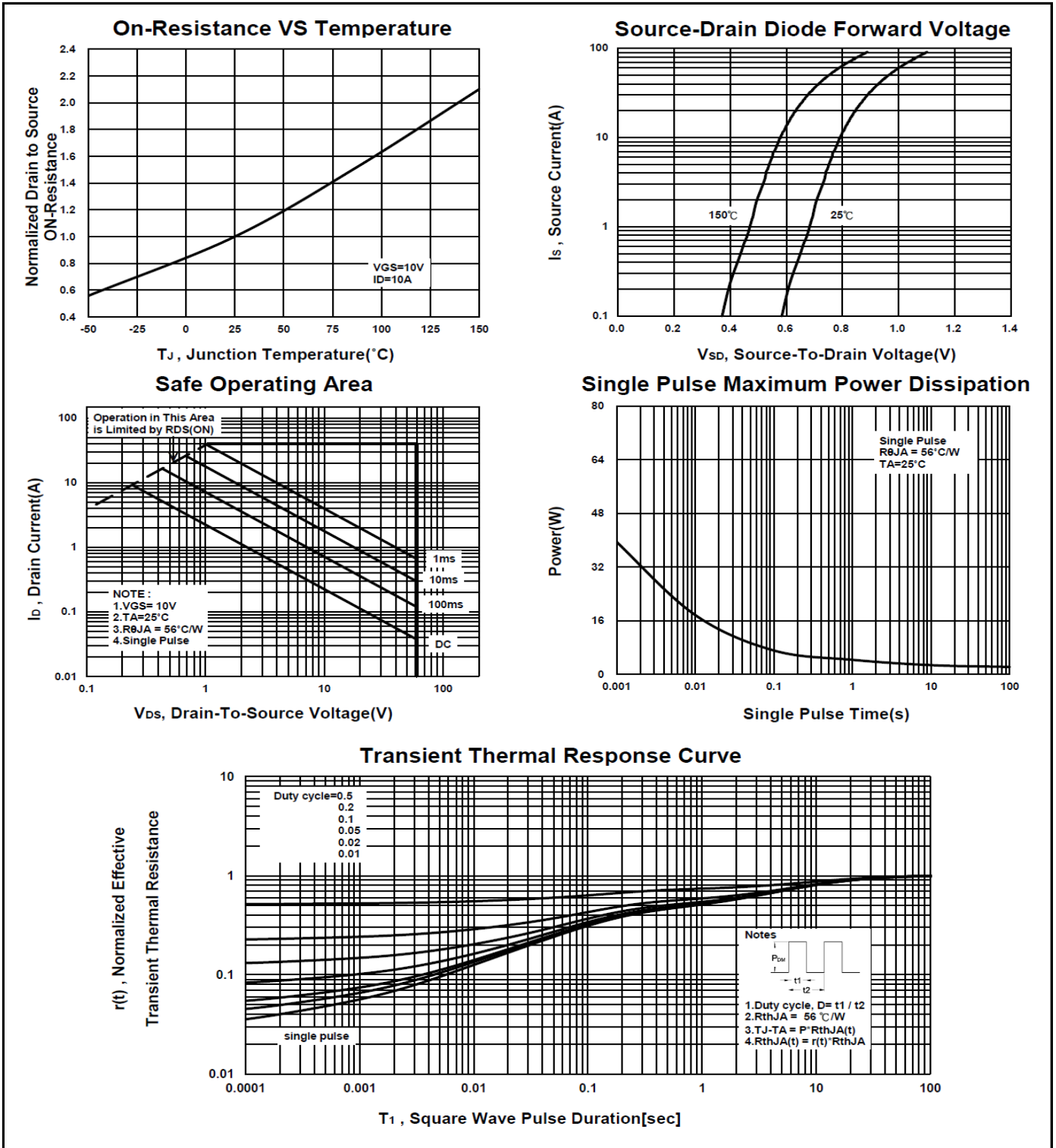
# P1406BV

## N-Channel Enhancement Mode MOSFET



# P1406BV

## N-Channel Enhancement Mode MOSFET



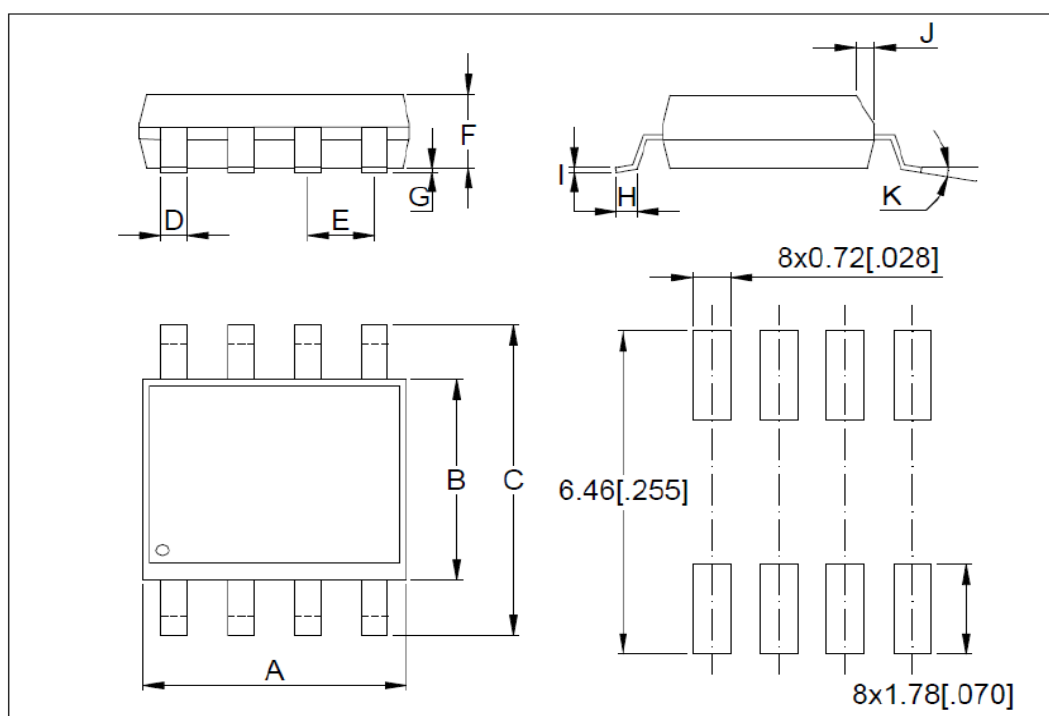
# P1406BV

## N-Channel Enhancement Mode MOSFET

### Package Dimension

### SOP-8 MECHANICAL DATA

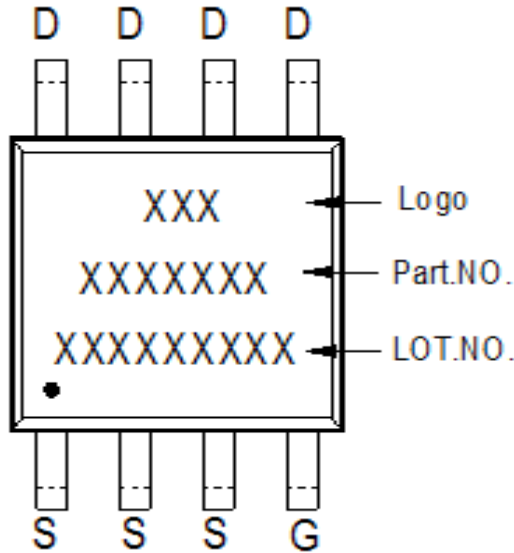
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	H	0.4	0.6	0.93
B	3.8	3.9	4.0	I	0.19	0.21	0.25
C	5.79	6.0	6.2	J	0.25	0.375	0.5
D	0.33	0.4	0.51	K	0°	3°	18°
E	1.25	1.27	1.29				
F	1.1	1.3	1.65				
G	0.05	0.15	0.25				



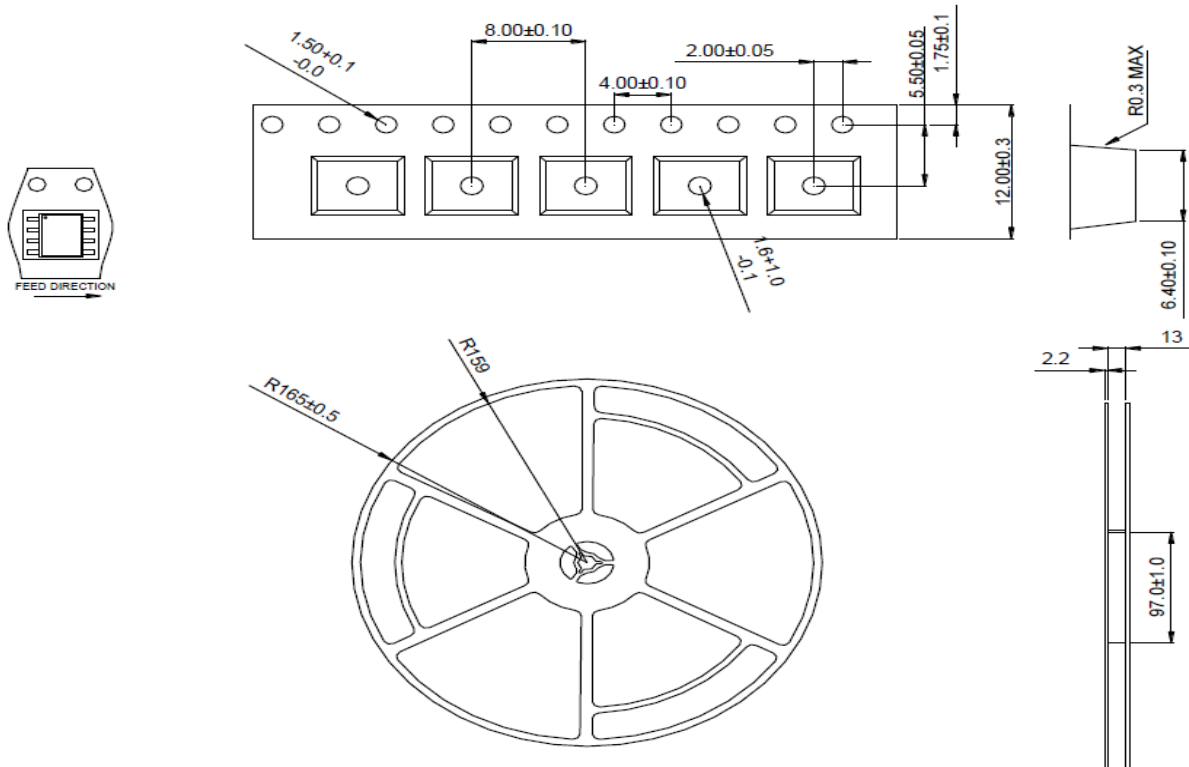
# P1406BV

## N-Channel Enhancement Mode MOSFET

### A. Marking Information



### B. Tape&Reel Information:2500pcs/Reel

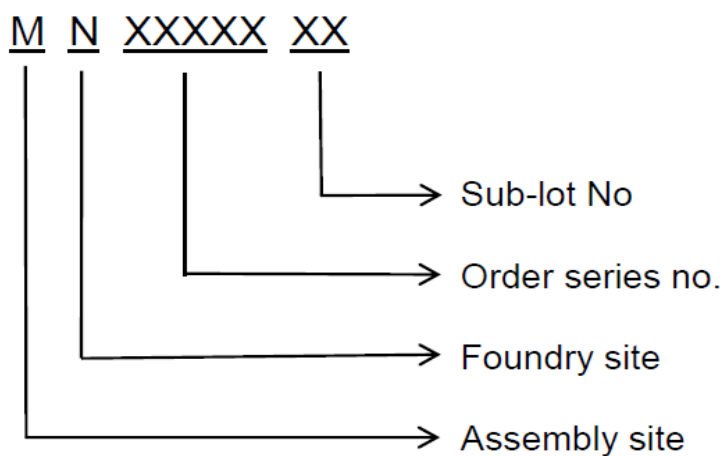


# P1406BV

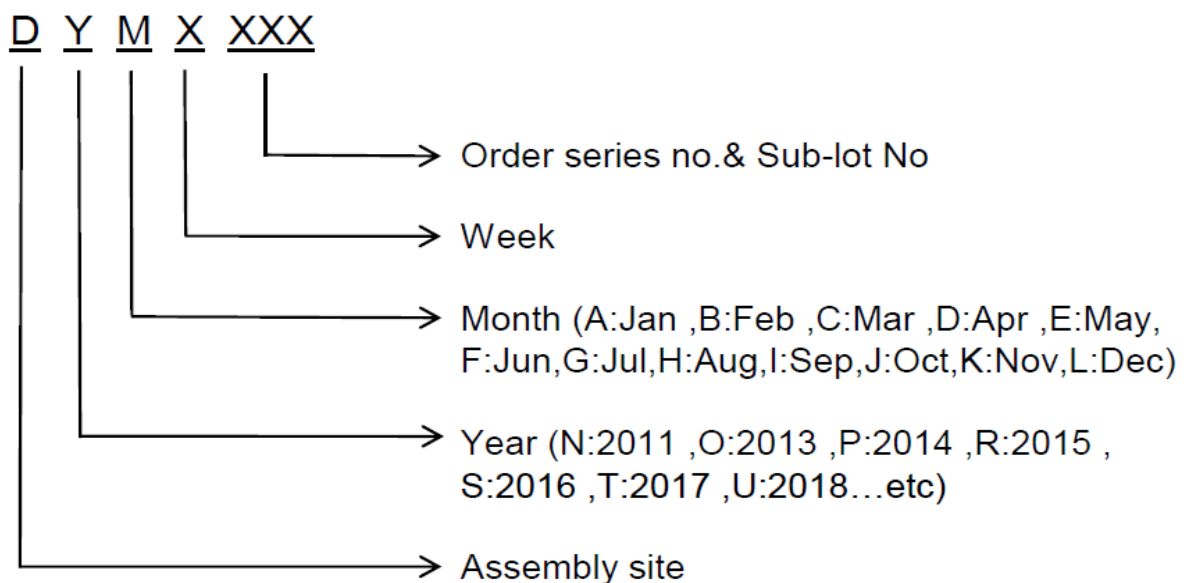
## N-Channel Enhancement Mode MOSFET

### C. Lot No.&Date Code rule

#### 1.Lot No.



#### 2.Date Code





# P1406BV

## N-Channel Enhancement Mode MOSFET

### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文"0"和数字"0", "G和"Q"的字型即可)
3	U-NIKC	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	RoHS label	 long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial
12	Scan information	Device / Lot / D/C / QTY , Insert " / " between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least